

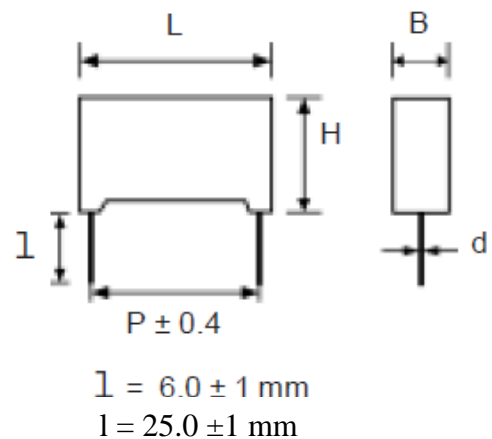
**APPLICATION:** In electronic equipment and appliances for suppression of electromagnetic interference (EMI/RFI) across the line & line by pass, SMPS, electronic ballast.

**FEATURE:**

- Non-Inductive construction
- Self- Healing property
- Low Dissipation Factor and high Insulation Resistance
- Encased in fire-retardant plastic case and sealed with epoxy resin.

**TECHNICAL DETAILS:**

<b>Dielectr</b>	: Polypropylene
<b>Electrodes</b>	: Vacuum deposited zinc aluminium
<b>Encapsulation</b>	: Plastic box and Epoxy (MPX-X2/M
<b>Flame Retardancy</b>	: Conforming to UL 94 V-0
<b>Temperature</b>	: -40 <sup>0</sup> C TO 85 <sup>0</sup> C
<b>Tolerance</b>	: ±10% & ±20%
<b>Test Voltage</b>	: 2120 VDC for 2 seconds
<b>I.R. at 100V</b>	: > 3 x 10 <sup>4</sup> M Ohms.
<b>Dissipation Factor</b>	: < 0.0005 at 1 KHz.

**HITECH ELECTROCOMPONENTS PVT. LTD.**

**DIMENSION (max. in mm):****For 300 VAC, 10/ 15 mm pitch**

Capacitance	L mm	W mm	H mm	Pitch	φ d
0.01 μF	13	5	11	10	0.6
0.033μF	18	5	12	15	0.8
0.047 μF	13	5	11	10	0.6
0.047μF	18	5	12	15	0.8
0.1 μF	18	6	12	15	0.8
0.22 μF	18	7	14	15	0.8
0.33μF	18	9	17	15	0.8
0.47μF	18	9	17	15	0.8

**For 275/300 VAC, 22.5/ 27.5 mm pitch**

Capacitance	L mm	W mm	H mm	Pitch	φ d
0.47μF	26.5	10	18.5	22.5	0.8
0.68 μF	26.5	10	18.5	22.5	0.8
1.0 μF	26.5	10	18.5	22.5	0.8
1.0 μF	32	13	22	27.5	0.8

**For 440/500VAC, 10/ 22.5/ 27.5 mm pitch**

Capacitance	L mm	W mm	H mm	Pitch	φ d
0.01μF	13	5	11	10	0.6
0.41μF	26.5	8.5	17	22.5	0.8
0.47μF	26.5	10	18.5	22.5	0.8
1.25μF	32	13	22	27.5	0.8

**HITECH ELECTROCOMPONENTS PVT. LTD.**